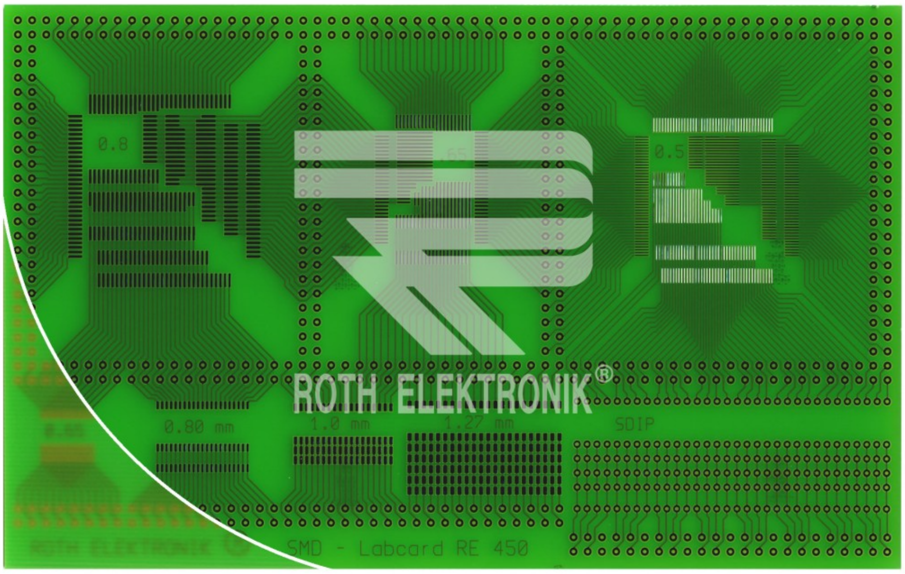
Prototyping Board for SMT (low cost)



RE450-LF

- EPOXY fibre-glass FR4 1.50 mm single-sided 35 µm CU without holes
- hot air leveling (HAL-leadfree)

- adaption plate for ap. 40 different QFP-, SOP-, SSOP-, SDIP-casings
- solder side hot air leveling (HAL-leadfree) and solder stop mask coated
- the following casings are adaptable:
- QFP- 0.80 mm Pitch: 44, 56, 64, 72, 80, 94, 100, 120-Pin
- QFP- 0.85 mm Pitch: 48, 54, 56, 64, 68, 80, 100-Pin
- QFP- 0.50 mm Pitch: 48, 64, 72, 80, 100, 120, 144, 160-Pin
- SOP- 1.27 mm Pitch: max. 44-Pin in 225, 300, 375, 450, 525, 600 mil.
- SOP- 1.00 mm Pitch: max. 36-Pin in 225, 300, 375 mil.
- SSOP- 0.80 mm Pitch: max. 42-Pin in 300, 450 mil.
- SSOP- 0.65 mm Pitch: max. 30-Pin in 225, 300 mil.
- SDIP- 1.778 mm Raster: max. 64-Pin in 300, 400, 500, 600, 750 mil.
- size 100 x 160 mm